

HIGH DENSITY INTERNAL BALL GRID ARRAY
INTEGRATED CIRCUIT PACKAGE

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ABSTRACT OF THE DISCLOSURE

5 An integrated circuit package (30) comprising a substrate
(70) having peripheral openings (86) and first and second
surfaces (92, 94), a plurality of routing strips (82) being
integral with the substrate (70), a plurality of pads (100)
centrally disposed on the first surface (92) and electrically
connected with at least one of the routing strips (82), a chip
(50) having bonding pads (120) adhered to the second surface
(84) of the substrate (70), wire bonding (80) electrically
connecting at least one bonding pad (120) to at least one of
the routing strips (82) and potting material (90) filling the
openings (86) to adhere the chip (50) to the substrate (70)
and surrounding the wire bonding (80), is disclosed.

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